

PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

A wafer held on a delivery pad is lifted from a holding surface, and when a lower surface of the wafer has been spaced in its entirety from the holding surface, an air flow rate regulating valve is opened to eject air from the holding surface. As the distance between the holding surface and the wafer spaced from the holding surface increases by lifting of a delivery unit, the degree of opening of the air flow rate regulating valve is adjusted to increase a flow rate of air from the holding surface, thereby spacing the wafer from the holding surface in a short period of time without rupturing the wafer.

[Fig. 2]